

In the Claims:

Please cancel claims 43-57 without prejudice.

Please add new claims 58-75 as follows:

Sub D1
C1
58. (New) An electronic component comprising:
a substrate including a conductive area; and
a resilient, conductive contact structure comprising a base portion attached to said conductive area, a tip portion displaced away from said substrate and said conductive area, and a beam portion between said base portion and said tip portion, wherein:
a length of said beam portion extends from said base portion to said tip portion,
and
a width of said beam portion decreases along said length from said base portion to said tip portion.

Sub E1
59. (New) The electronic component of claim 58, wherein said conductive area comprises a terminal.

60. (New) The electronic component of claim 58 further comprising a terminal on said substrate, said terminal being electrically connected to said conductive area.

61. (New) The electronic component of claim 58, wherein said tip portion includes a pointed end.

Sub E1
62. (New) The electronic component of claim 58, wherein said substrate composes a semiconductor device.

Sub E1
63. (New) The electronic component of claim 58, wherein said contact structure comprises a metal layer.

64. (New) The electronic component of claim 63, wherein said contact structure comprises a plurality of metal layers.

E! 65. (New) The electronic component of claim 58 further comprising a plurality of said contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

66. (New) The electronic component of claim 58, wherein said tip portion comprises a beveled peripheral edge.

67. (New) An electronics system comprising:
a first substrate including a conductive area; and
a resilient, conductive contact structure comprising a base portion attached to said conductive area, a tip portion displaced away from said first substrate, and a beam portion between said base portion and said tip portion, wherein a length of said beam portion extends from said base portion to said tip portion, and a width of said beam portion decreases along said length from said base portion to said tip portion; and
a second substrate including a conductive contact element in physical contact with said contact structure and deflecting said contact structure, said contact structure exerting a force against said contact element due to said resiliency of said contact structure.

Sub 68. (New) The electronics system of claim 67, wherein said conductive area comprises a terminal.

69. (New) The electronics system of claim 67 further comprising a terminal on said first substrate, said terminal being electrically connected to said conductive area.

70. (New) The electronics system of claim 67, wherein said tip portion includes a pointed end.

Sub 71. (New) The electronics system of claim 67, wherein said substrate composes a semiconductor device.

72. (New) The electronics system of claim 67, wherein said contact structure comprises a metal layer.

73. (New) The electronics system of claim 67, wherein said contact structure comprises a plurality of metal layers.

74. (New) The electronics system of claim 67 further comprising a plurality of said contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

75. (New) The electronics system of claim 67, wherein said tip portion comprises a beveled peripheral edge.